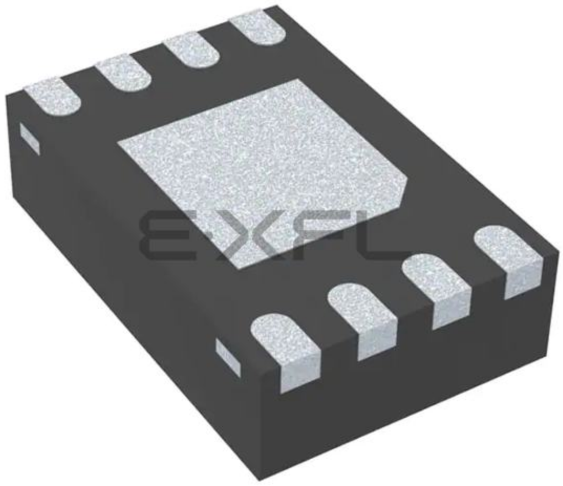

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	5
Program Memory Size	1.5KB (1K x 12)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	41 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	8-VFDFN Exposed Pad
Supplier Device Package	8-DFN (2x3)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic12f509-e-mc

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1.0 GENERAL DESCRIPTION

The PIC12F508/509/16F505 devices from Microchip Technology are low-cost, high-performance, 8-bit, fully-static, Flash-based CMOS microcontrollers. They employ a RISC architecture with only 33 single-word/ single-cycle instructions. All instructions are single cycle (200 μs) except for program branches, which take two cycles. The PIC12F508/509/16F505 devices deliver performance an order of magnitude higher than their competitors in the same price category. The 12-bit wide instructions are highly symmetrical, resulting in a typical 2:1 code compression over other 8-bit microcontrollers in its class. The easy to use and easy to remember instruction set reduces development time significantly.

The PIC12F508/509/16F505 products are equipped with special features that reduce system cost and power requirements. The Power-on Reset (POR) and Device Reset Timer (DRT) eliminate the need for external Reset circuitry. There are four oscillator configurations to choose from (six on the PIC16F505), including INTRC Internal Oscillator mode and the power-saving LP (Low-Power) Oscillator mode. Power-Saving Sleep mode, Watchdog Timer and code protection features improve system cost, power and reliability.

The PIC12F508/509/16F505 devices are available in the cost-effective Flash programmable version, which is suitable for production in any volume. The customer can take full advantage of Microchip's price leadership in Flash programmable microcontrollers, while benefiting from the Flash programmable flexibility.

The PIC12F508/509/16F505 products are supported by a full-featured macro assembler, a software simulator, an in-circuit emulator, a 'C' compiler, a low-cost development programmer and a full featured programmer. All the tools are supported on IBM® PC and compatible machines.

1.1 Applications

The PIC12F508/509/16F505 devices fit in applications ranging from personal care appliances and security systems to low-power remote transmitters/receivers. The Flash technology makes customizing application programs (transmitter codes, appliance settings, receiver frequencies, etc.) extremely fast and convenient. The small footprint packages, for through hole or surface mounting, make these microcontrollers perfect for applications with space limitations. Low cost, low power, high performance, ease-of-use and I/O flexibility make the PIC12F508/509/16F505 devices very versatile even in areas where no microcontroller use has been considered before (e.g., timer functions, logic and PLDs in larger systems and coprocessor applications).

TABLE 1-1: PIC12F508/509/16F505 DEVICES

		PIC12F508	PIC12F509	PIC16F505
Clock	Maximum Frequency of Operation (MHz)	4	4	20
Memory	Flash Program Memory (words)	512	1024	1024
	Data Memory (bytes)	25	41	72
Peripherals	Timer Module(s)	TMR0	TMR0	TMR0
	Wake-up from Sleep on Pin Change	Yes	Yes	Yes
Features	I/O Pins	5	5	11
	Input Pins	1	1	1
	Internal Pull-ups	Yes	Yes	Yes
	In-Circuit Serial Programming	Yes	Yes	Yes
	Number of Instructions	33	33	33
	Packages	8-pin PDIP, SOIC, MSOP, DFN	8-pin PDIP, SOIC, MSOP, DFN	14-pin PDIP, SOIC, TSSOP

The PIC12F508/509/16F505 devices have Power-on Reset, selectable Watchdog Timer, selectable code-protect, high I/O current capability and precision internal oscillator.
The PIC12F508/509/16F505 devices use serial programming with data pin RB0/GP0 and clock pin RB1/GP1.

FIGURE 3-1: PIC12F508/509 BLOCK DIAGRAM

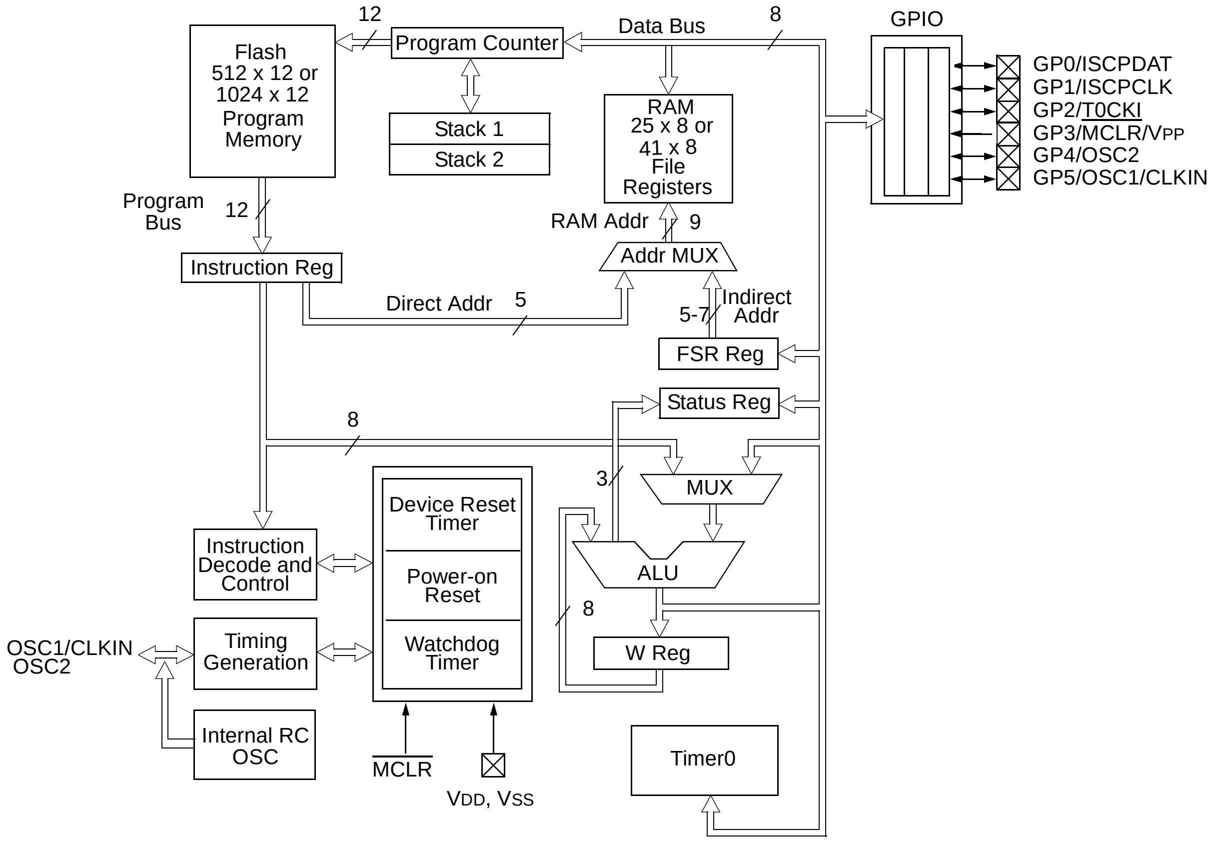

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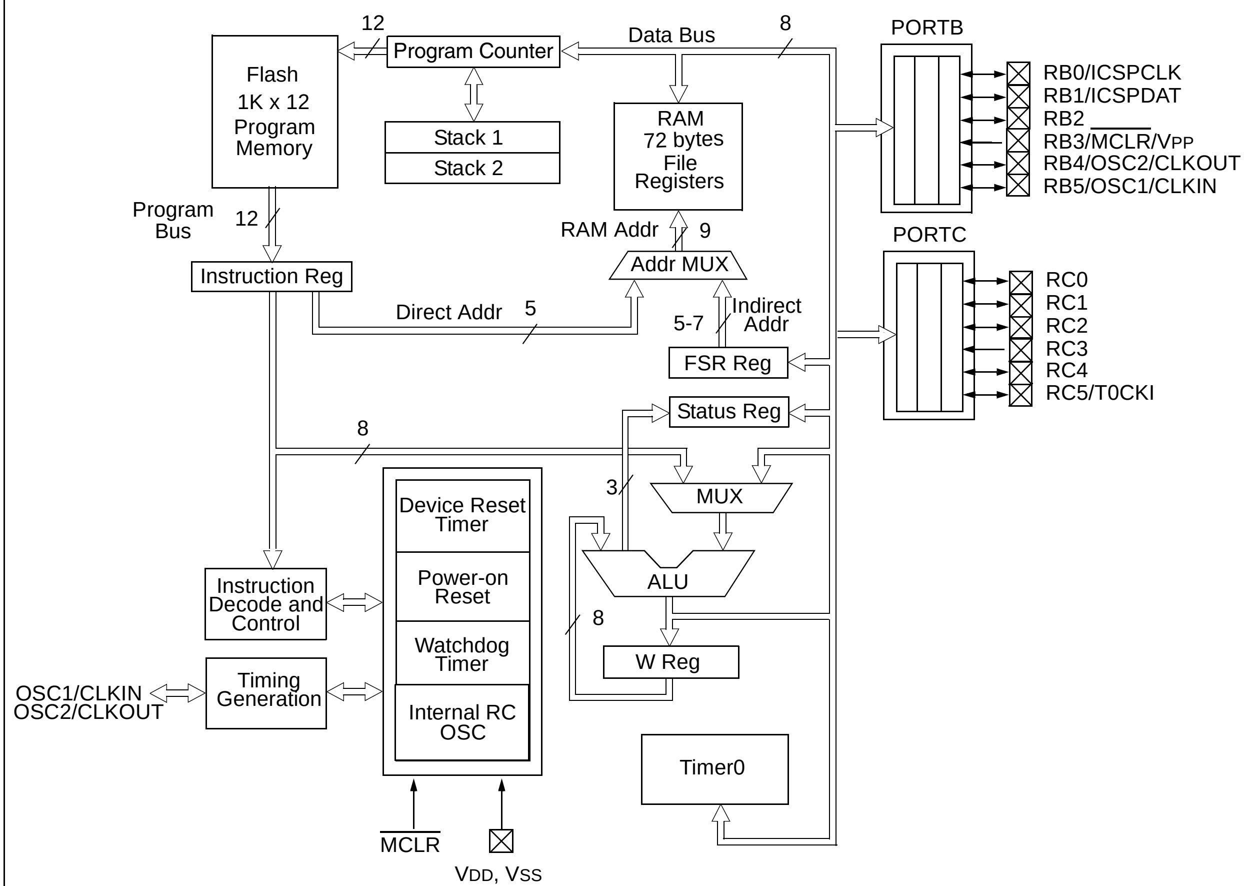
FIGURE 3-2: PIC16F505 BLOCK DIAGRAM



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4.3.2 SPECIAL FUNCTION REGISTERS

The Special Function Registers (SFRs) are registers used by the CPU and peripheral functions to control the operation of the device (Table 4-1).

The Special Function Registers can be classified into two sets. The Special Function Registers associated with the "core" functions are described in this section. Those related to the operation of the peripheral features are described in the section for each peripheral feature.

TABLE 4-1: SPECIAL FUNCTION REGISTER (SFR) SUMMARY (PIC12F508/509)

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-On Reset(2)	Page #
00h	INDF	Uses Contents of FSR to Address Data Memory (not a physical register)								xxxx xxxx	28
01h	TMR0	8-bit Real-Time Clock/Counter								xxxx xxxx	35
02h(1)	PCL	Low-order 8 bits of PC								1111 1111	27
03h	STATUS	GPWUF	—	PA0(5)	$\overline{TO}$	$\overline{PD}$	Z	DC	C	0-01 1xxx(3)	22
04h	FSR	Indirect Data Memory Address Pointer								111x xxxx	28
04h(4)	FSR	Indirect Data Memory Address Pointer								110x xxxx	28
05h	OSCCAL	CAL6	CAL5	CAL4	CAL3	CAL2	CAL1	CAL0	—	1111 111-	26
06h	GPIO	—	—	GP5	GP4	GP3	GP2	GP1	GP0	--xx xxxx	31
N/A	TRISGPIO	—	—	I/O Control Register						--11 1111	31
N/A	OPTION	$\overline{GPWU}$	$\overline{GPPU}$	TOCS	TOSE	PSA	PS2	PS1	PS0	1111 1111	24

Legend: – = unimplemented, read as '0', x = unknown, u = unchanged, q = value depends on condition.

Note 1: The upper byte of the Program Counter is not directly accessible. See **Section 4.7 "Program Counter"** for an explanation of how to access these bits.

2: Other (non Power-up) Resets include external Reset through $\overline{MCLR}$, Watchdog Timer and wake-up on pin change Reset.

3: If Reset was due to wake-up on pin change, then bit 7 = 1. All other Resets will cause bit 7 = 0.

4: PIC12F509 only.

5: This bit is used on the PIC12F509. For code compatibility do not use this bit on the PIC12F508.

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REGISTER 4-2: STATUS REGISTER (ADDRESS: 03h) (PIC16F505)

R/W-0	R/W-0	R/W-0	R-1	R-1	R/W-x	R/W-x	R/W-x
RBWUF	—	PA0	$\overline{TO}$	$\overline{PD}$	Z	DC	C
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7 **RBWUF:** PORTB Reset bit
1 = Reset due to wake-up from Sleep on pin change
0 = After power-up or other Reset

bit 6 **Reserved**: Do not use

bit 5 **PA0**: Program Page Preselect bits
1 = Page 1 (200h-3FFh)
0 = Page 0 (000h-1FFh)
Each page is 512 bytes.
Using the PA0 bit as a general purpose read/write bit in devices which do not use it for program page preselect is not recommended, since this may affect upward compatibility with future products.

bit 4 **$\overline{TO}$**: Time-Out bit
1 = After power-up, CLRWDT instruction, or SLEEP instruction
0 = A WDT time-out occurred

bit 3 **$\overline{PD}$**: Power-Down bit
1 = After power-up or by the CLRWDT instruction
0 = By execution of the SLEEP instruction

bit 2 **Z**: Zero bit
1 = The result of an arithmetic or logic operation is zero
0 = The result of an arithmetic or logic operation is not zero

bit 1 **DC**: Digit Carry/$\overline{Borrow}$ bit (for ADDWF and SUBWF instructions)
ADDWF:
1 = A carry from the 4th low-order bit of the result occurred
0 = A carry from the 4th low-order bit of the result did not occur
SUBWF:
1 = A borrow from the 4th low-order bit of the result did not occur
0 = A borrow from the 4th low-order bit of the result occurred

bit 0 **C**: Carry/$\overline{Borrow}$ bit (for ADDWF, SUBWF and RRF, RLF instructions)

ADDWF:	SUBWF:	RRF or RLF:
1 = A carry occurred	1 = A borrow did not occur	Load bit with LSb or MSb, respectively
0 = A carry did not occur	0 = A borrow occurred	

4.7 Program Counter

As a program instruction is executed, the Program Counter (PC) will contain the address of the next program instruction to be executed. The PC value is increased by one every instruction cycle, unless an instruction changes the PC.

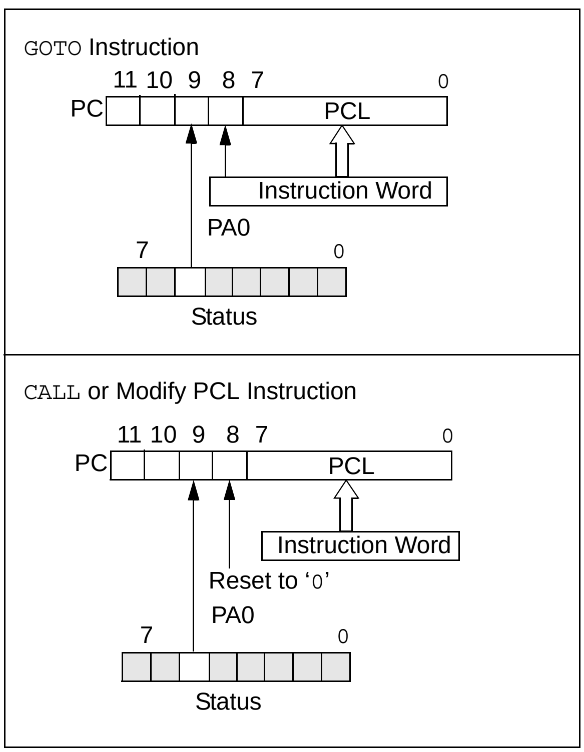
For a `GOTO` instruction, bits 8:0 of the PC are provided by the `GOTO` instruction word. The Program Counter (PCL) is mapped to PC<7:0>. Bit 5 of the STATUS register provides page information to bit 9 of the PC (Figure 4-6).

For a `CALL` instruction, or any instruction where the PCL is the destination, bits 7:0 of the PC again are provided by the instruction word. However, PC<8> does not come from the instruction word, but is always cleared (Figure 4-6).

Instructions where the PCL is the destination, or modify PCL instructions, include `MOVWF PC, ADDWF PC` and `BSF PC,5.`

Note:	Because PC<8> is cleared in the `CALL` instruction or any modify PCL instruction, all subroutine calls or computed jumps are limited to the first 256 locations of any program memory page (512 words long).

FIGURE 4-6: LOADING OF PC BRANCH INSTRUCTIONS



4.7.1 EFFECTS OF RESET

The PC is set upon a Reset, which means that the PC addresses the last location in the last page (i.e., the oscillator calibration instruction). After executing `MOVLW XX`, the PC will roll over to location 00h and begin executing user code.

The STATUS register page preselect bits are cleared upon a Reset, which means that page 0 is pre-selected.

Therefore, upon a Reset, a `GOTO` instruction will automatically cause the program to jump to page 0 until the value of the page bits is altered.

4.8 Stack

The PIC12F508/509/16F505 devices have a 2-deep, 12-bit wide hardware PUSH/POP stack.

A `CALL` instruction will PUSH the current value of Stack 1 into Stack 2 and then PUSH the current PC value, incremented by one, into Stack Level 1. If more than two sequential `CALL`s are executed, only the most recent two return addresses are stored.

A `RETLW` instruction will POP the contents of Stack Level 1 into the PC and then copy Stack Level 2 contents into Stack Level 1. If more than two sequential `RETLW`s are executed, the stack will be filled with the address previously stored in Stack Level 2. Note that the W register will be loaded with the literal value specified in the instruction. This is particularly useful for the implementation of data look-up tables within the program memory.

Note 1:	There are no Status bits to indicate stack overflows or stack underflow conditions.
2:	There are no instruction mnemonics called PUSH or POP. These are actions that occur from the execution of the `CALL` and `RETLW` instructions.

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NOTES:

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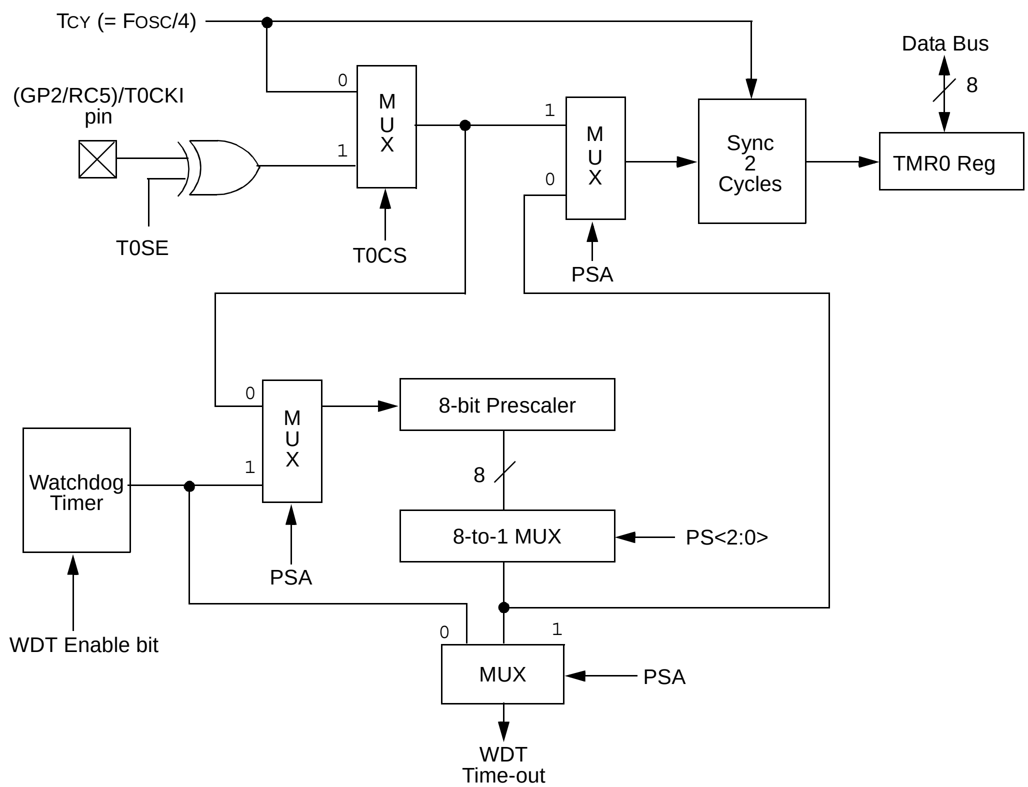
FIGURE 6-5: BLOCK DIAGRAM OF THE TIMER0/WDT PRESCALER(1), (2)



Note 1: T0CS, T0SE, PSA, PS<2:0> are bits in the OPTION register.

2: T0CKI is shared with pin RC5 on the PIC16F505 and pin GP2 on the PIC12F508/509.

TABLE 7-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR – PIC12F508/509/16F505(2)

Osc Type	Resonator Freq.	Cap. Range C1	Cap. Range C2
LP	32 kHz(1)	15 pF	15 pF
XT	200 kHz 1 MHz 4 MHz	47-68 pF 15 pF 15 pF	47-68 pF 15 pF 15 pF
HS(3)	20 MHz	15-47 pF	15-47 pF

Note 1: For $V_{DD} > 4.5V$, C1 = C2 ≈ 30 pF is recommended.

2: These values are for design guidance only. Rs may be required to avoid over-driving crystals with low drive level specification. Since each crystal has its own characteristics, the user should consult the crystal manufacturer for appropriate values of external components.

3: PIC16F505 only.

7.2.3 EXTERNAL CRYSTAL OSCILLATOR CIRCUIT

Either a prepackaged oscillator or a simple oscillator circuit with TTL gates can be used as an external crystal oscillator circuit. Prepackaged oscillators provide a wide operating range and better stability. A well-designed crystal oscillator will provide good performance with TTL gates. Two types of crystal oscillator circuits can be used: one with parallel resonance, or one with series resonance.

Figure 7-3 shows implementation of a parallel resonant oscillator circuit. The circuit is designed to use the fundamental frequency of the crystal. The 74AS04 inverter performs the 180-degree phase shift that a parallel oscillator requires. The 4.7 kΩ resistor provides the negative feedback for stability. The 10 kΩ potentiometers bias the 74AS04 in the linear region. This circuit could be used for external oscillator designs.

FIGURE 7-3: EXTERNAL PARALLEL RESONANT CRYSTAL OSCILLATOR CIRCUIT

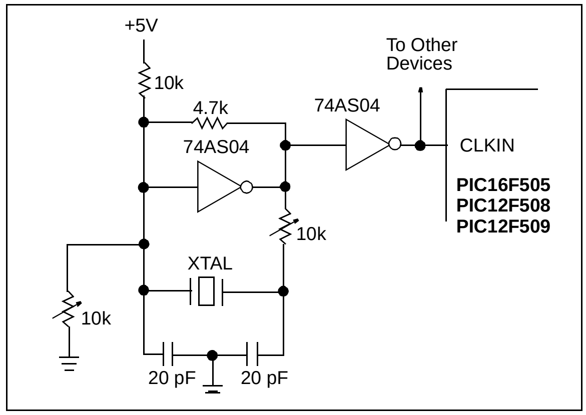
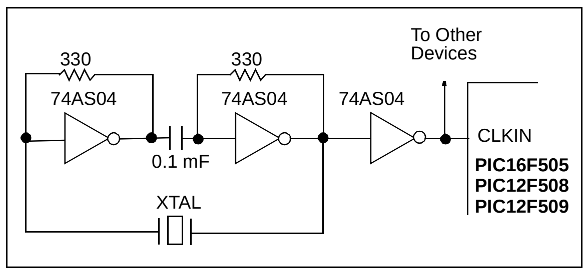


Figure 7-4 shows a series resonant oscillator circuit. This circuit is also designed to use the fundamental frequency of the crystal. The inverter performs a 180-degree phase shift in a series resonant oscillator circuit. The 330 Ω resistors provide the negative feedback to bias the inverters in their linear region.

FIGURE 7-4: EXTERNAL SERIES RESONANT CRYSTAL OSCILLATOR CIRCUIT



7.2.4 EXTERNAL RC OSCILLATOR

For timing insensitive applications, the RC device option offers additional cost savings. The RC oscillator frequency is a function of the supply voltage, the resistor (R_{EXT}) and capacitor (C_{EXT}) values, and the operating temperature. In addition to this, the oscillator frequency will vary from unit-to-unit due to normal process parameter variation. Furthermore, the difference in lead frame capacitance between package types will also affect the oscillation frequency, especially for low C_{EXT} values. The user also needs to take into account variation due to tolerance of external R and C components used.

Figure 7-5 shows how the R/C combination is connected to the PIC12F508/509/16F505 devices. For R_{EXT} values below 3.0 kΩ, the oscillator operation may become unstable, or stop completely. For very high R_{EXT} values (e.g., 1 MΩ), the oscillator becomes sensitive to noise, humidity and leakage. Thus, we recommend keeping R_{EXT} between 5.0 kΩ and 100 kΩ.

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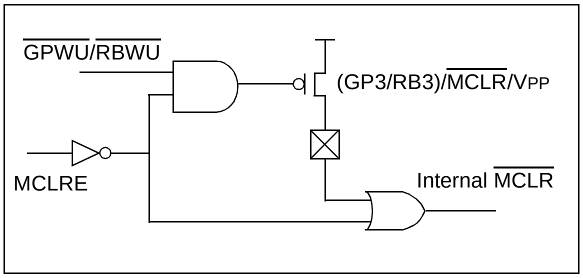
7.3.1 MCLR ENABLE

This Configuration bit, when unprogrammed (left in the '1' state), enables the external MCLR function. When programmed, the MCLR function is tied to the internal VDD and the pin is assigned to be an input only. See Figure 7-6.

FIGURE 7-6: MCLR SELECT



7.4 Power-on Reset (POR)

The PIC12F508/509/16F505 devices incorporate an on-chip Power-on Reset (POR) circuitry, which provides an internal chip Reset for most power-up situations.

The on-chip POR circuit holds the chip in Reset until VDD has reached a high enough level for proper operation. To take advantage of the internal POR, program the (GP3/RB3)/MCLR/VPP pin as MCLR and tie through a resistor to VDD, or program the pin as (GP3/RB3). An internal weak pull-up resistor is implemented using a transistor (refer to Table 10-2 for the pull-up resistor ranges). This will eliminate external RC components usually needed to create a Power-on Reset. A maximum rise time for VDD is specified. See **Section 10.0 "Electrical Characteristics"** for details.

When the devices start normal operation (exit the Reset condition), device operating parameters (voltage, frequency, temperature,...) must be met to ensure operation. If these conditions are not met, the devices must be held in Reset until the operating parameters are met.

A simplified block diagram of the on-chip Power-on Reset circuit is shown in Figure 7-7.

The Power-on Reset circuit and the Device Reset Timer (see **Section 7.5 "Device Reset Timer (DRT)"**) circuit are closely related. On power-up, the Reset latch is set and the DRT is reset. The DRT timer begins counting once it detects MCLR to be high. After the time-out period, which is typically 18 ms, it will reset the Reset latch and thus end the on-chip Reset signal.

A power-up example where MCLR is held low is shown in Figure 7-8. VDD is allowed to rise and stabilize before bringing MCLR high. The chip will actually come out of Reset TDRT msec after MCLR goes high.

In Figure 7-9, the on-chip Power-on Reset feature is being used (MCLR and VDD are tied together or the pin is programmed to be (GP3/RB3). The VDD is stable before the start-up timer times out and there is no problem in getting a proper Reset. However, Figure 7-10 depicts a problem situation where VDD rises too slowly. The time between when the DRT senses that MCLR is high and when MCLR and VDD actually reach their full value, is too long. In this situation, when the start-up timer times out, VDD has not reached the VDD (min) value and the chip may not function correctly. For such situations, we recommend that external RC circuits be used to achieve longer POR delay times (Figure 7-9).

Note:	When the devices start normal operation (exit the Reset condition), device operating parameters (voltage, frequency, temperature, etc.) must be met to ensure operation. If these conditions are not met, the device must be held in Reset until the operating conditions are met.

For additional information, refer to Application Notes AN522 *"Power-Up Considerations"* (DS00522) and AN607 *"Power-up Trouble Shooting"* (DS00607).

FIGURE 7-7: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT

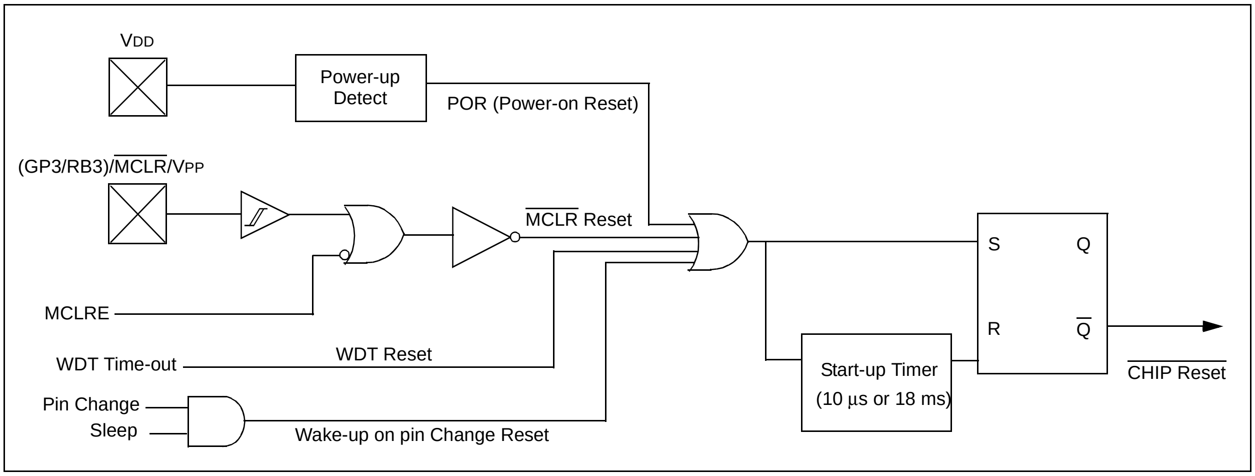


FIGURE 7-8: TIME-OUT SEQUENCE ON POWER-UP (MCLR PULLED LOW)

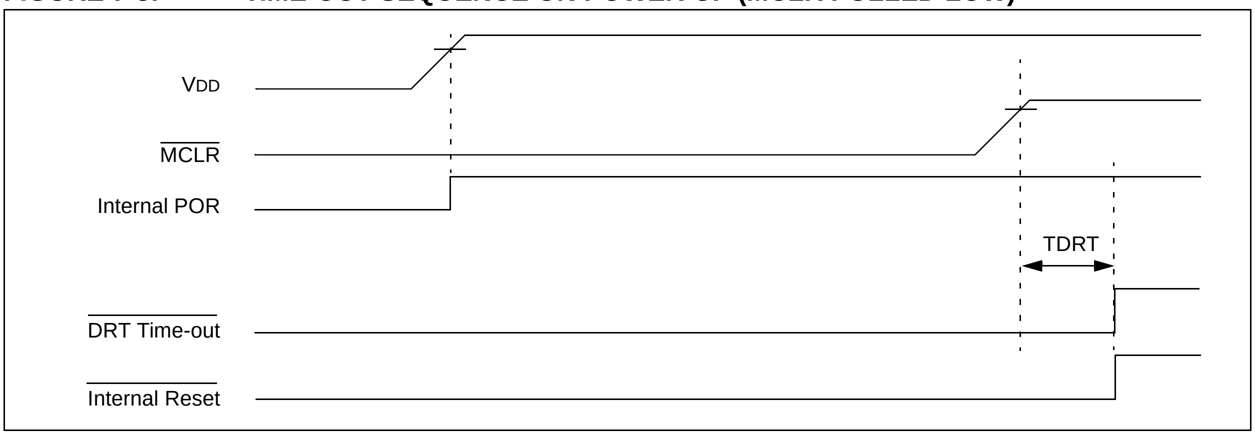
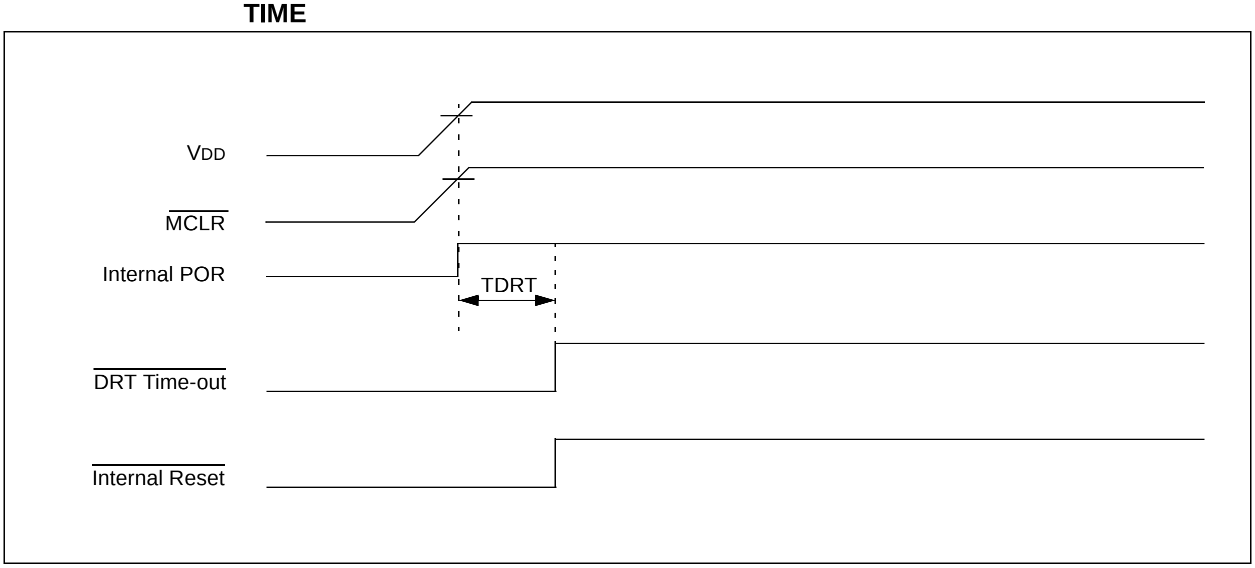


FIGURE 7-9: TIME-OUT SEQUENCE ON POWER-UP (MCLR TIED TO VDD): FAST VDD RISE TIME



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IORWF	Inclusive OR W with f
Syntax:	[*label*] IORWF f,d
Operands:	$0 \le f \le 31$ $d \in [0,1]$
Operation:	(W).OR. (f) → (dest)
Status Affected:	Z
Description:	Inclusive OR the W register with register 'f'. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'.

MOVF	Move f
Syntax:	[*label*] MOVF f,d
Operands:	$0 \le f \le 31$ $d \in [0,1]$
Operation:	(f) → (dest)
Status Affected:	Z
Description:	The contents of register 'f' are moved to destination 'd'. If 'd' is '0', destination is the W register. If 'd' is '1', the destination is file register 'f'. 'd' = 1 is useful as a test of a file register, since status flag Z is affected.

MOVLW	Move Literal to W
Syntax:	[*label*] MOVLW k
Operands:	$0 \le k \le 255$
Operation:	k → (W)
Status Affected:	None
Description:	The eight-bit literal 'k' is loaded into the W register. The "don't cares" will assembled as '0's.

MOVWF	Move W to f
Syntax:	[*label*] MOVWF f
Operands:	$0 \le f \le 31$
Operation:	(W) → (f)
Status Affected:	None
Description:	Move data from the W register to register 'f'.

NOP	No Operation
Syntax:	[*label*] NOP
Operands:	None
Operation:	No operation
Status Affected:	None
Description:	No operation.

OPTION	Load OPTION Register
Syntax:	[*label*] OPTION
Operands:	None
Operation:	(W) → OPTION
Status Affected:	None
Description:	The content of the W register is loaded into the OPTION register.

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9.11 PICSTART Plus Development Programmer

The PICSTART Plus Development Programmer is an easy-to-use, low-cost, prototype programmer. It connects to the PC via a COM (RS-232) port. MPLAB Integrated Development Environment software makes using the programmer simple and efficient. The PICSTART Plus Development Programmer supports most PIC devices in DIP packages up to 40 pins. Larger pin count devices, such as the PIC16C92X and PIC17C76X, may be supported with an adapter socket. The PICSTART Plus Development Programmer is CE compliant.

9.12 PICkit 2 Development Programmer

The PICkit™ 2 Development Programmer is a low-cost programmer and selected Flash device debugger with an easy-to-use interface for programming many of Microchip's baseline, mid-range and PIC18F families of Flash memory microcontrollers. The PICkit 2 Starter Kit includes a prototyping development board, twelve sequential lessons, software and HI-TECH's PICC™ Lite C compiler, and is designed to help get up to speed quickly using PIC® microcontrollers. The kit provides everything needed to program, evaluate and develop applications using Microchip's powerful, mid-range Flash memory family of microcontrollers.

9.13 Demonstration, Development and Evaluation Boards

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM™ and dsPICDEM™ demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ® security ICs, CAN, IrDA®, PowerSmart battery management, SEEVAL® evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Check the Microchip web page (www.microchip.com) for the complete list of demonstration, development and evaluation kits.

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FIGURE 11-12: TTL INPUT THRESHOLD VIN vs. VDD

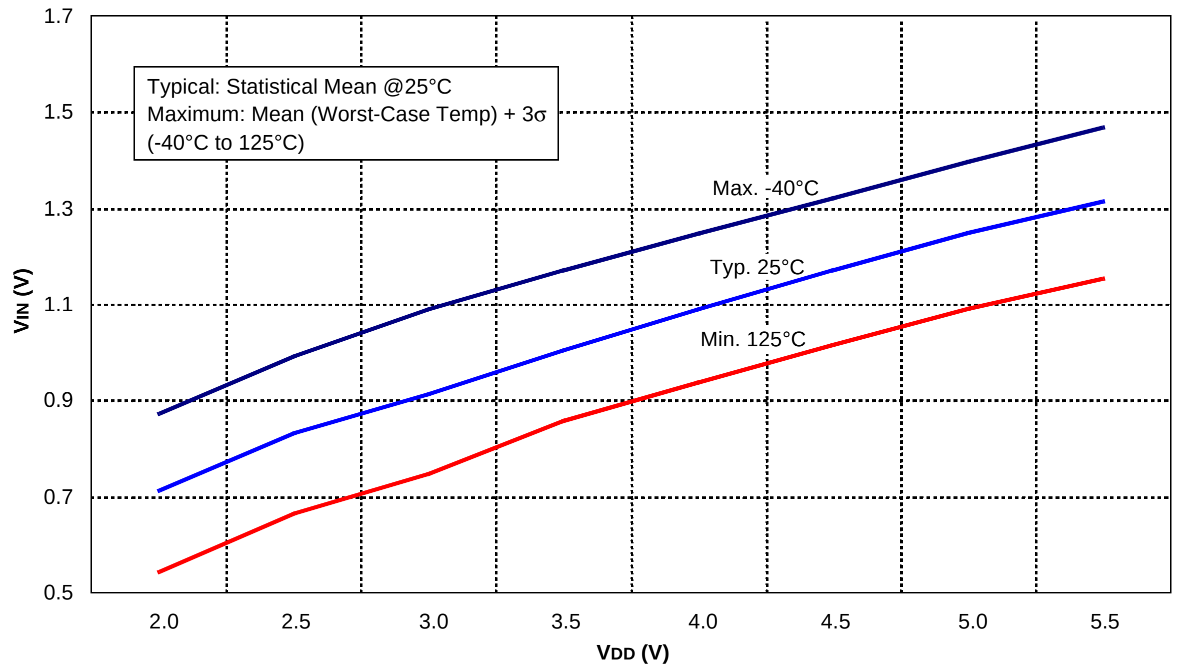
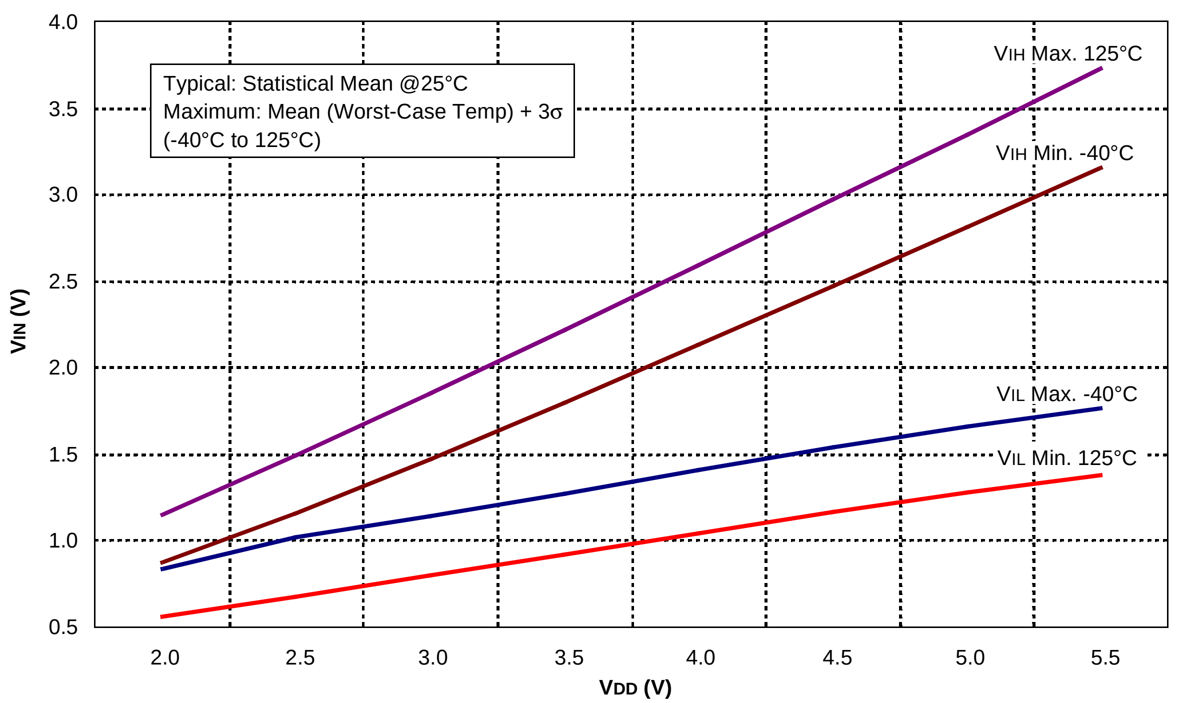


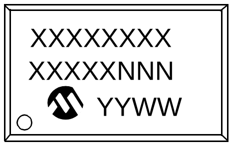
FIGURE 11-13: SCHMITT TRIGGER INPUT THRESHOLD VIN vs. VDD



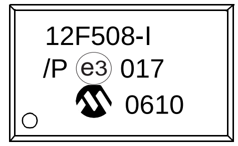
12.0 PACKAGING INFORMATION

12.1 Package Marking Information

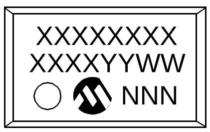
8-Lead PDIP



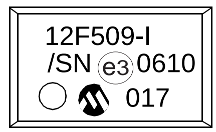
Example



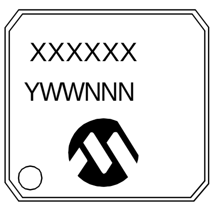
8-Lead SOIC (3.90 mm)



Example

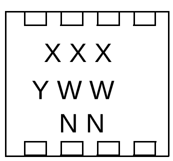


8-Lead MSOP

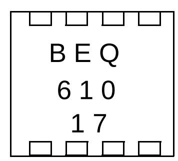


Example

8-Lead 2x3 DFN*



Example



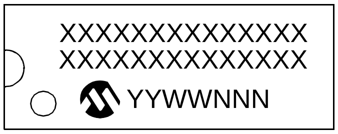
Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
	e3	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line thus limiting the number of available characters for customer specific information.

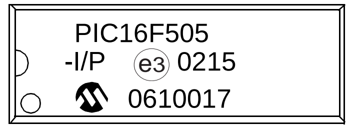
* Standard PIC® device marking consists of Microchip part number, year code, week code, and traceability code. For PIC device marking beyond this, certain price adders apply. Please check with your Microchip Sales Office. For QTP devices, any special marking adders are included in QTP price.

12.1 Package Marking Information (Continued)

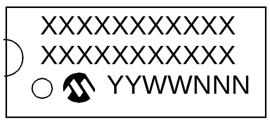
14-Lead PDIP (300 mil)



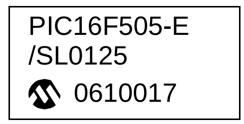
Example



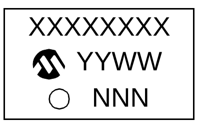
14-Lead SOIC (3.90 mm)



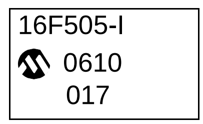
Example



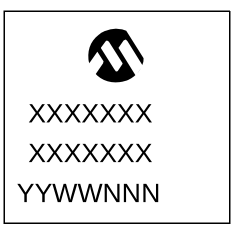
14-Lead TSSOP (4.4 mm)



Example



16-Lead QFN



Example

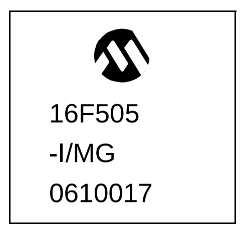


TABLE 12-1: 8-LEAD 2X3 DFN (MC) TOP MARKING

Part Number	Marking
PIC12F508 (T) - I/MC	BN0
PIC12F508-E/MC	BP0
PIC12F509 (T) - I/MC	BQ0
PIC12F509-E/MC	BR0

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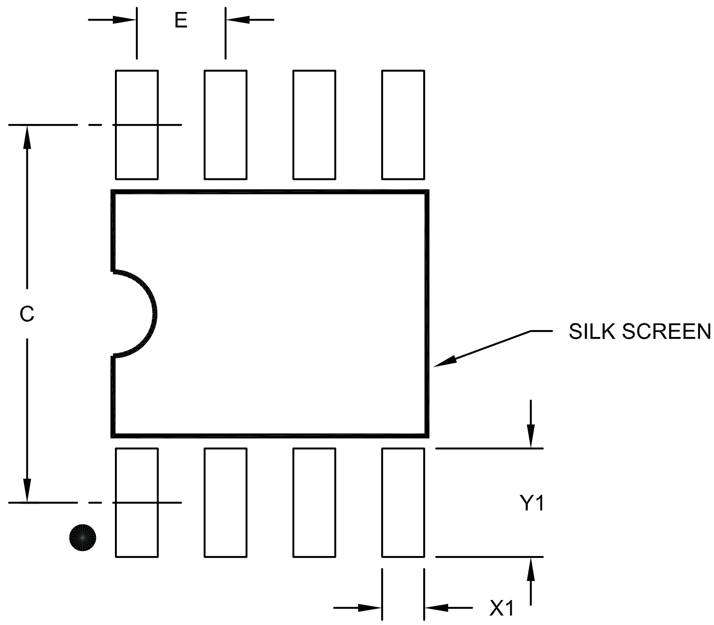
8-Lead Plastic Small Outline (SN) – Narrow, 3.90 mm Body [SOIC]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

	Units	MILLIMETERS		
	Dimension Limits	MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Contact Pad Spacing	C		5.40	
Contact Pad Width (X8)	X1			0.60
Contact Pad Length (X8)	Y1			1.55

Notes:

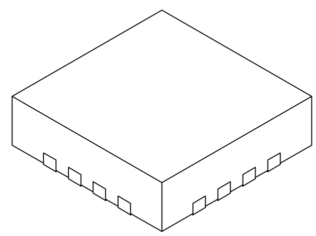
1. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2057A

16-Lead Plastic Quad Flat, No Lead Package (MG) - 3x3x0.9 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		16	
Pitch	e		0.50 BSC	
Overall Height	A	0.80	0.85	0.90
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.20 REF	
Overall Width	E		3.00 BSC	
Exposed Pad Width	E2	1.00	1.10	1.50
Overall Length	D		3.00 BSC	
Exposed Pad Length	D2	1.00	1.10	1.50
Contact Width	b	0.18	0.25	0.30
Contact Length	L	0.25	0.35	0.45
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-142A Sheet 2 of 2

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NOTES:

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